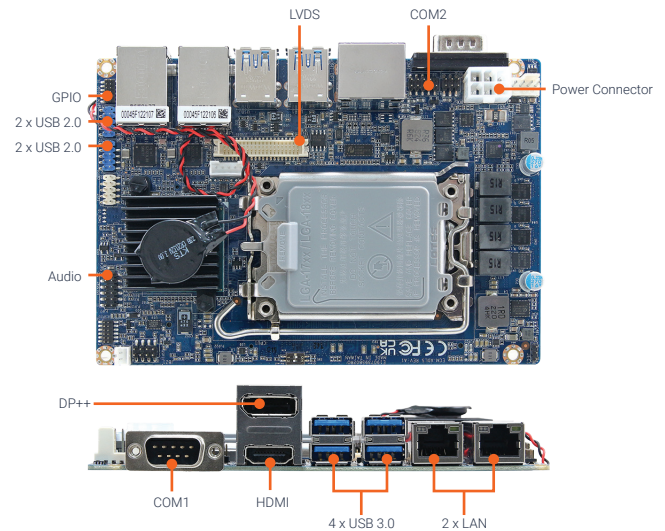


Features

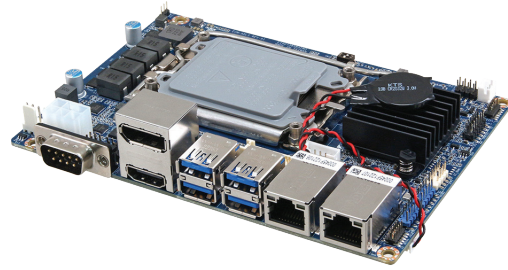
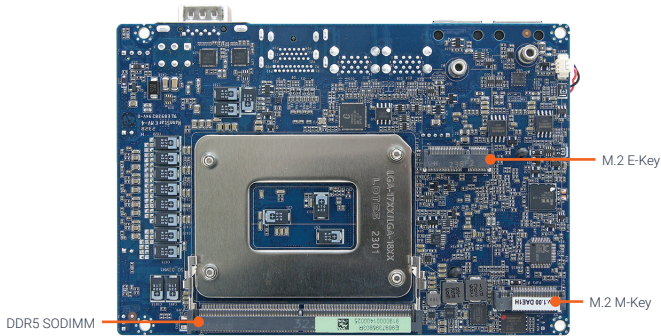
- LGA 1700 socket supports 12th Gen Intel® Core™ i9/i7/i5/i3/ Pentium®/Celeron® Processor, 13th Gen Intel® Core™ i3-13100TE Processor, up to 35W TDP
- Intel® Q670E/H610E PCH
- Top Layer Soldered Socket
- 1 x DDR5 4800MHz SODIMM socket supports up to 32GB
- Supports 3 Independent Displays: 1 x DP++, 1 x HDMI, 1 x 2CH LVDS, eDP optional
- M.2 E-Key, M.2 M-Key
- 2 x 2.5G Gigabit Ethernet
- 2 x RS-232/422/485
- +12V DC-In



Specifications

System	
CPU	LGA 1700 socket supports 12th Gen Intel® Core™ Processor up to 35W TDP: Intel® Celeron G6900TE 2.4GHz Processor Intel® Pentium G7400TE 3.0GHz Processor Intel® Core™ i3-12100TE 4.0GHz Processor Intel® Core™ i5-12500TE 4.5GHz Processor Intel® Core™ i7-12700TE 4.6GHz Processor Intel® Core™ i9-12900TE 4.8GHz Processor 13th Gen Intel® Core™ Processor up to 35W TDP: Intel® Core™ i3-13100TE 2.40GHz Processor Note: CPU cooler is included.
Chipset	Intel® Q670E Chipset or Intel® H610E Chipset
System Memory	1 x 262-pin DDR5 4800MHz SODIMM supports up to 32GB Non-ECC
BIOS	AMI BIOS, 256Mbit SPI Flash ROM
Expansion Slots & Storage	1 x M.2 E-Key (2230) supports Wi-Fi module, 2 x PCIe x1 Gen3, USB 2.0 1 x M.2 M-Key (2280) supports Gen3 PCIe x4 NVMe or SATA device
H/W Status Monitor	H/W Reset, 1sec. ~ 65535sec and 1sec. or 1min./step
Watchdog Timer	CPU & system temperature monitoring Voltages monitoring
TPM	fTPM
Supported OS	Win 11, Win 10, Linux
Display	
Chipset	Intel® 12th Generation CPU integrated
Interface	1 x DP 1.4b : 4096 x 2304@60 Hz, supports DP++ 1 x HDMI 2.0 : 4096 x 2304@60 Hz 1 x LVDS: 1920 x 1080 Dual channel 18/24-bits LVDS or 1 x eDP 1920 x 1080@60Hz (2 Lanes), default LVDS Note: JLVDS1 Supports 1 x LVDS or 1 x eDP, share the same connector
Multi-Display	Support 3 Independent Display
Audio	
Audio Codec	Realtek HD Audio
Interface	Mic-In, Line-In, Line-Out

Ethernet	
LAN Chipset	2 x Intel® Ethernet Controller I226-LM (2.5GbE)
LAN Port	2 x RJ45
External I/O	
Display	1 x DP++, 1 x HDMI
USB	4 x USB 3.2 Gen 2 (Please Note: Intel® H610E SKU supports 2 x Gen2 & 2 x Gen1 USB 3.2)
LAN	2 x RJ45
COM Port	1 x RS-232/422/485
Internal I/O	
Display	1 x LVDS Header 1 x eDP Header (Optional)
USB	2 x USB 2.0 Headers (4 Ports)
COM	1 x RS-232/422/485
GPIO	1 x 8-bits GPIO Header
DC-in	1 x +12V DC-in Header



Mechanical & Environment

Power Requirement	DC in +12V Please Note: Only use 12V DC-in for the ECM-ADLS SBC, please do not use Switching Power Supply.
Operating Temp.	0°C ~ 60°C (32°F ~ 140°F) with 0.5m/s air flow
Storage Temp.	-40° C ~ 75° C (-40°F ~ 167°F)
Operating Humidity	40°C @ 95% Relative Humidity, Non-condensing
Form Factor	3.5" Single Board Computer (SBC)
Certification Information	CE, FCC Class B, RoHS Compliant
Dimensions	5.7" x 4" (146mm x 102mm)
Weight	0.44lbs (0.2kg)

Ordering Info

ECM-ADLS-Q67	3.5" SBC with Intel® Q670E PCH, CPU cooler, 1 x 6-pin Power Cable, 1 x Flat Cable 9P(M)-PHD (10P/2.0mm).
ECM-ADLS-H61	3.5" SBC with Intel® H610E PCH, CPU cooler, 1 x 6-pin Power Cable, 1 x Flat Cable 9P(M)-PHD (10P/2.0mm).

* All product specifications and images are subject to change without notice. Last update:10/30/2023



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